# 2SK3546J

## Silicon N-Channel MOSFET

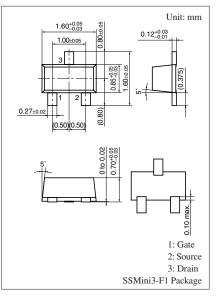
#### For switching

#### Features

- High-speed switching
- Wide frequency band

#### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Drain-source voltage	V <sub>DS</sub>	50	V	
Gate-source voltage (Drain open)	V <sub>GSO</sub>	±7	V	
Drain current	ID	100	mA	
Peak drain current	I <sub>DP</sub>	200	mA	
Power dissipation	P <sub>D</sub>	125	mW	
Channel temperature	T <sub>ch</sub>	125	°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	



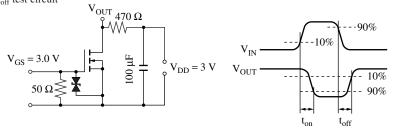
#### Marking Symbol: 5F

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

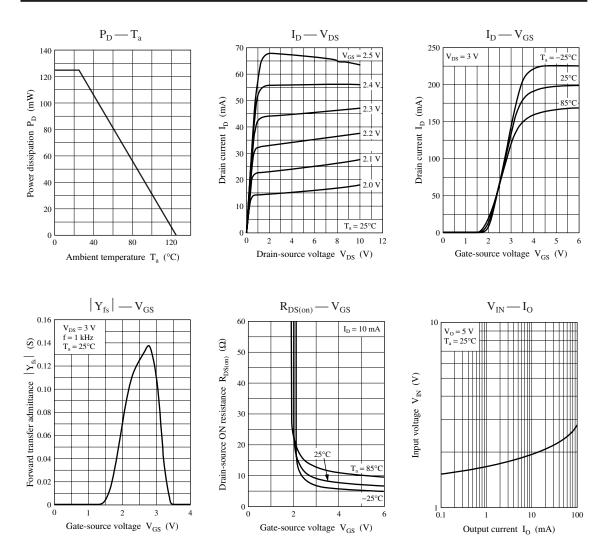
Parameter	Symbol	Conditions	Min	Тур	Мах	Unit
Drain-source surrender voltage	V <sub>DSS</sub>	$I_D = 10 \ \mu A, \ V_{GS} = 0$	50			V
Drain-source cutoff current	I <sub>DSS</sub>	$V_{DS} = 50 \text{ V}, V_{GS} = 0$			1.0	μΑ
Gate-source cutoff current	I <sub>GSS</sub>	$V_{GS} = \pm 7 V, V_{DS} = 0$			±5.0	μΑ
Gate threshold voltage	V <sub>th</sub>	$I_D = 1.0 \ \mu A, \ V_{DS} = 3 \ V$	0.9	1.2	1.5	V
Drain-source ON resistance	R <sub>DS(on)</sub>	$I_D = 10 \text{ mA}, V_{GS} = 2.5 \text{ V}$		8	15	Ω
		$I_D = 10 \text{ mA}, V_{GS} = 4.0 \text{ V}$		6	12	
Forward transfer admittance	Y <sub>fs</sub>	$I_D = 10 \text{ mA}, V_{DS} = 3 \text{ V}, f = 1 \text{ kHz}$	20	60		mS
Short-circuit forward transfer capacitance (Common source)	C <sub>iss</sub>	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$		12		pF
Short-circuit output capacitance (Common source)	C <sub>oss</sub>	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$		7		pF
Reverse transfer capacitance (Common source)	C <sub>rss</sub>	$V_{DS} = 3 V, V_{GS} = 0, f = 1 MHz$		3		pF
Turn-on time *	t <sub>on</sub>	$V_{DD} = 3 V, V_{GS} = 0 V \text{ to } 3 V, R_L = 470 \Omega$		200		ns
Turn-off time *	t <sub>off</sub>	$V_{DD} = 3 V, V_{GS} = 3 V \text{ to } 0 V, R_L = 470 \Omega$		200		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





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